



Bill of Material

TI DESIGNS

Fitted	Description	Designator	Manufacturer	PartNumber	Quantity	RoHS	PackageReference
Fitted	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	C1	AVX	06035C104KAT2A	1	Y	0603
Fitted	CAP, CERM, 0.033uF, 1000V, +/-10%, X7R, 1812	C2, C4	MuRata	GRM43DR73A333KW01L	2	Y	1812
Fitted	CAP, CERM, 0.82uF, 50V, +/-10%, X7R, 1210	C3	MuRata	GRM32RR71H824KA01L	1	Y	1210
Fitted	Diode, Zener, 3V, 500mW, SOD-123	D1, D2	Vishay-Semiconductor	MMSZ4683-V	2	Y	SOD-123
Fitted	Diode, TVS, Uni, 45V, 600W, SMB	D3, D5	Diodes Inc.	SMBJ45A-13-F	2	Y	SMB
Fitted	Diode, SMT TVS 400W, xx-A, yy-V	D4, D6	Diodes	SMAJxxxCA	2		SMA
Fitted	Terminal Block, 4x1, 2.54mm, TH	J1, J2, J3	On Shore Technology Inc	OSTVN02A150	3	Y	TERM_BLK, 2pos, 2.54mm
Fitted	RES, 10 ohm, 5%, 1W, 2512	R1, R3	Panasonic	ERJ-1TYJ100U	2	Y	2512
Fitted	RES, 0.1 ohm, 1%, 20W, TH	R2	Bourns	PWR220T-20-R100F	1	Y	TO-220AC
Fitted	Power Management, Current Monitor	U1	Texas Instruments	INA282-286	1		SOIC-8 (Package Drawing - D)

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